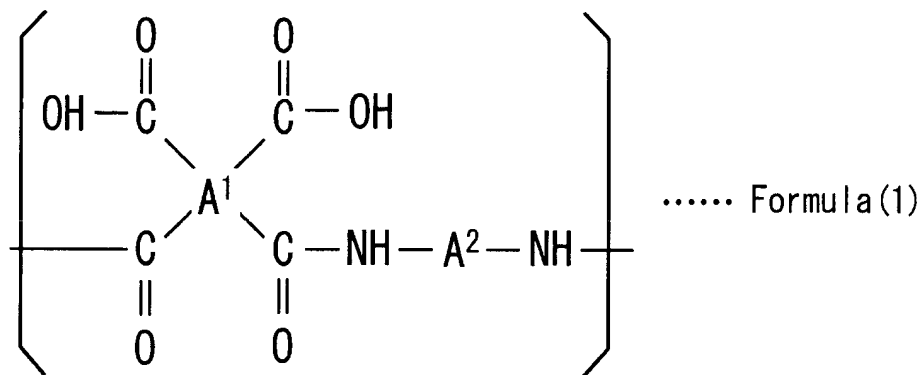


WHAT IS CLAIMED IS:

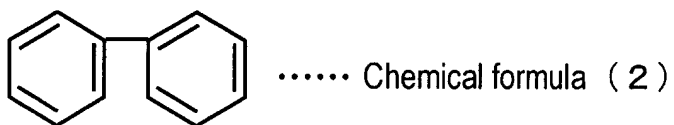
1. A resin composition containing an imidized polyimide precursor having a polymer structure unit represented by formula

5 (1) below:

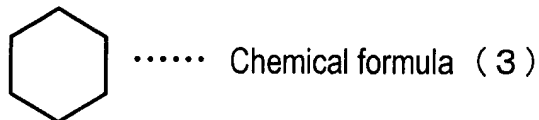


wherein the chemical structure represented by A¹ includes an aromatic compound and the chemical structure represented by A² includes an alicyclic compound, and a photosensitizer,

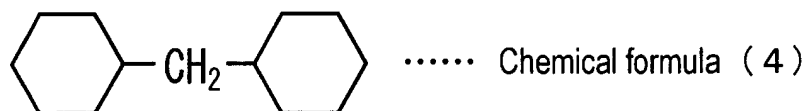
wherein the chemical structure represented by A¹ in formula (1) above
10 is biphenyl represented by chemical formula (2) below:



and the chemical structure represented by A² in formula (1) above is an alicyclic compound selected from either one of cyclohexane represented by chemical formula (3) below:



or 4,4'-methylenebiscyclohexane represented by chemical formula
15 (4) below:



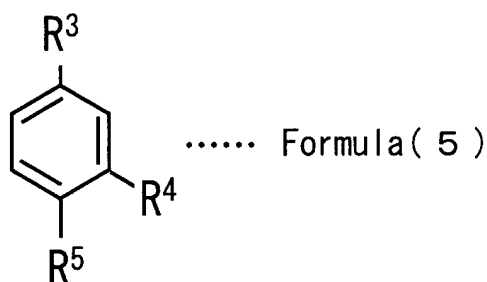
and wherein the polyimide precursor has an imidization degree of 7.5 % or more and 36 % or less as determined by equation (a) below:

$$\text{Equation (a): } (PS_1/PS_2)/(PI_1/PI_2) \times 100$$

wherein PS_1 and PI_1 represent the absorbances derived from the imide ring and PS_2 and PI_2 represent the absorbances derived from chemical structure A^2 in formula (1) above, and PS_1 and PS_2 represent the absorbances of the polyimide precursor to be tested for the imidization degree and PI_1 and PI_2 represent the absorbances of the polyimide precursor after complete imidization.

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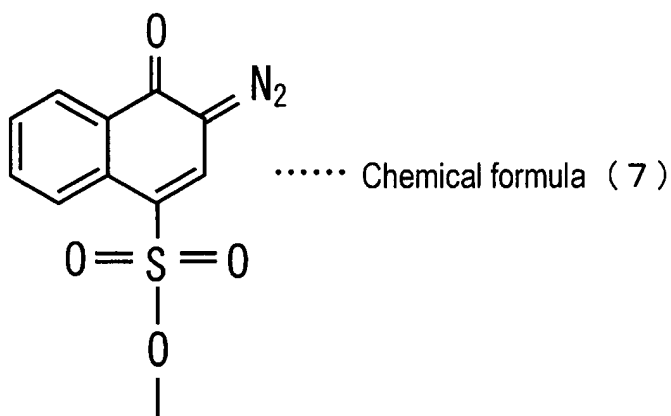
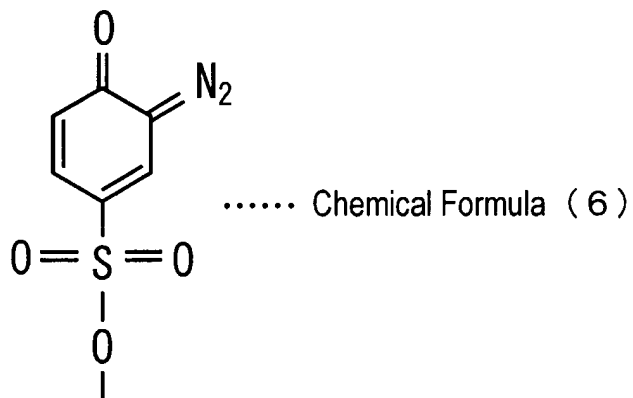
2. The resin composition of claim 1 wherein the photosensitizer is based on an o-quinone diazide compound represented by formula (5) below:

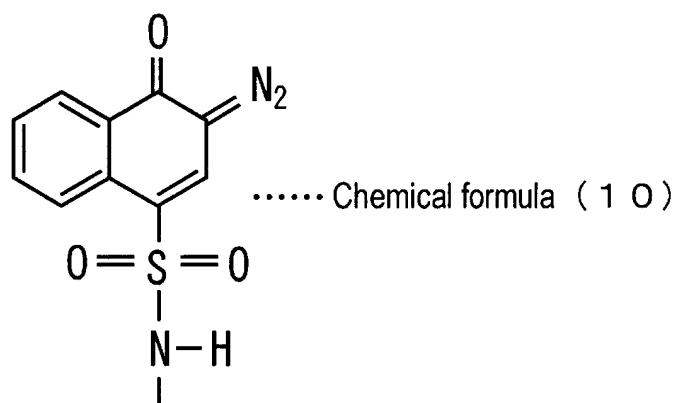
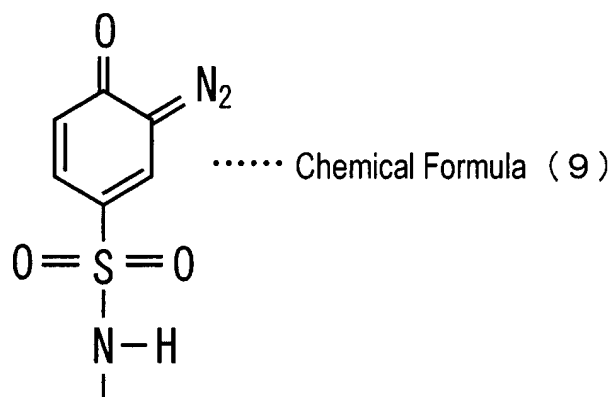
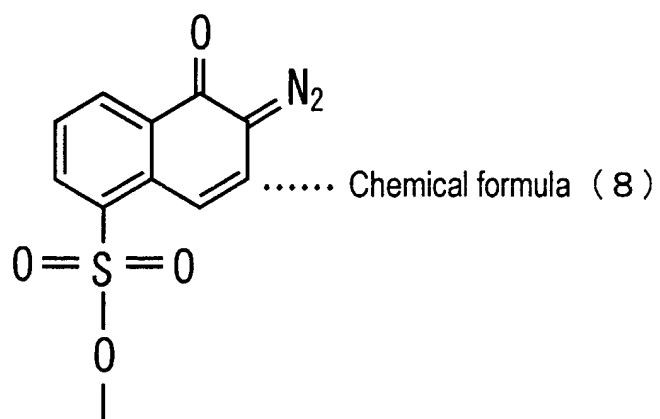


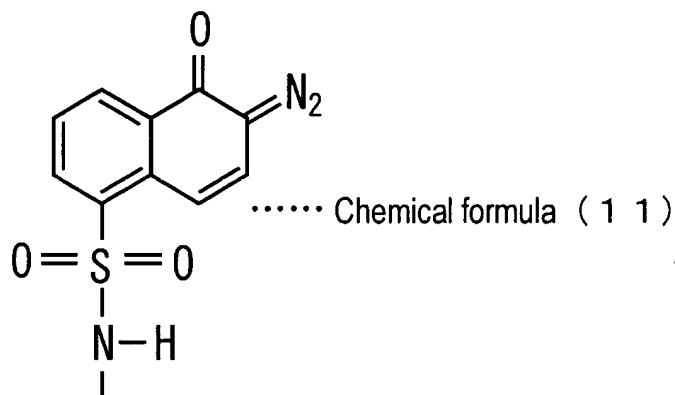
wherein substituent R^3 represents any one of substituents selected from the group consisting of methyl, hydroxyl, methylketone, cyano and the substituents represented by chemical formulae (6) - (8) below, substituent R^4 represents any one of substituents selected from the group consisting of hydrogen and the substituents represented by chemical formulae (6) - (8) below, and substituent R^5 represents any

one of substituents selected from the group consisting of hydrogen and the substituents represented by chemical formulae (6)-(11) below, provided that at least one of substituents R³- R⁵ represents any one of substituents selected from the group consisting of the

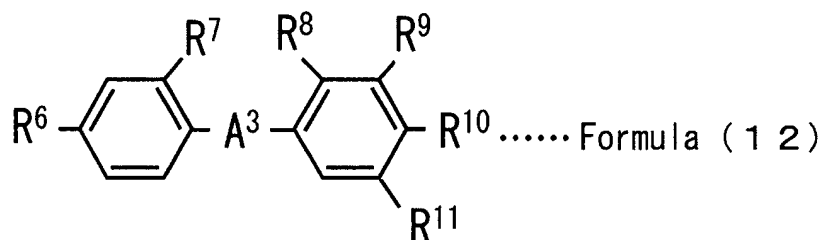
5 substituents represented by chemical formulae (6)-(8) below:



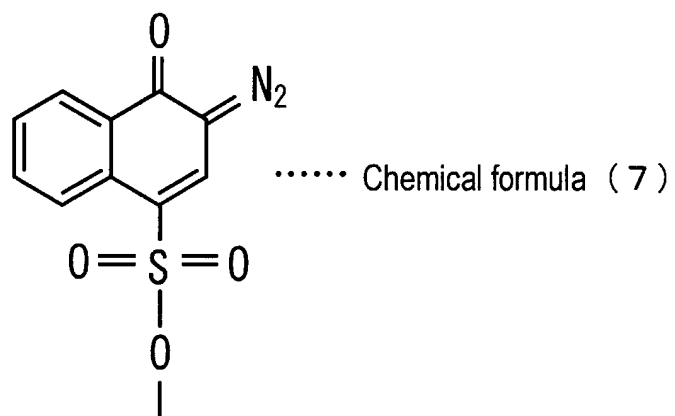
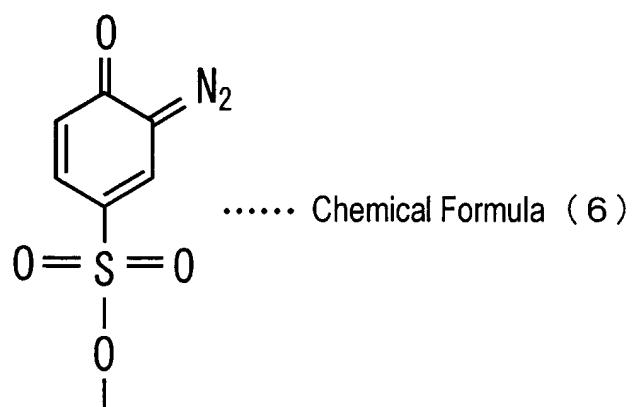
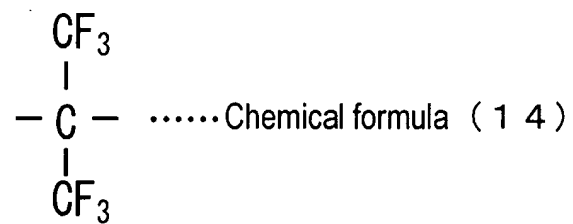
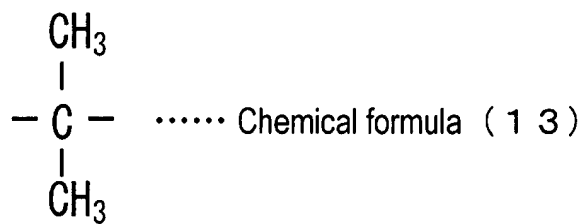


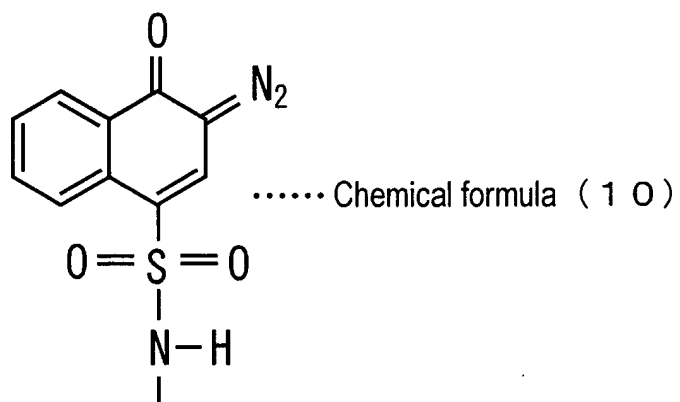
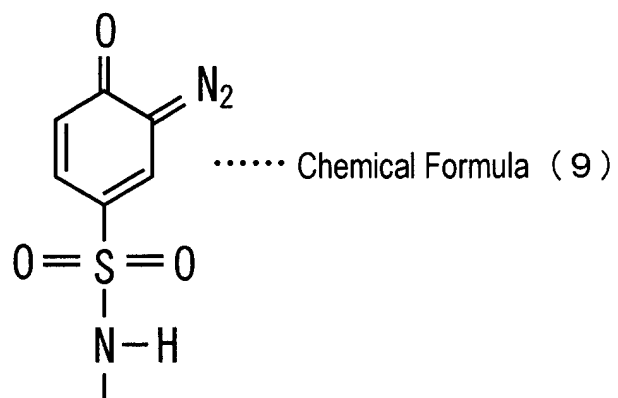
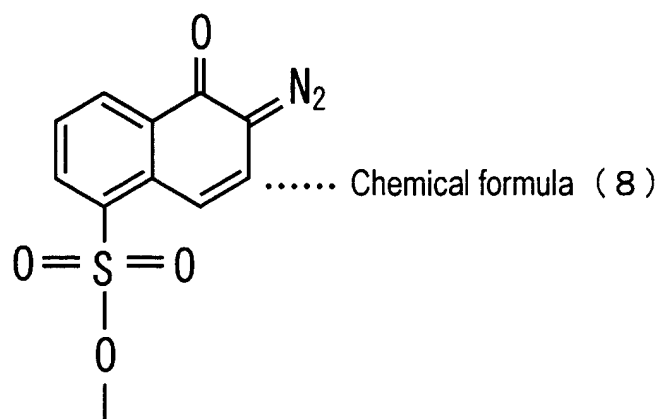


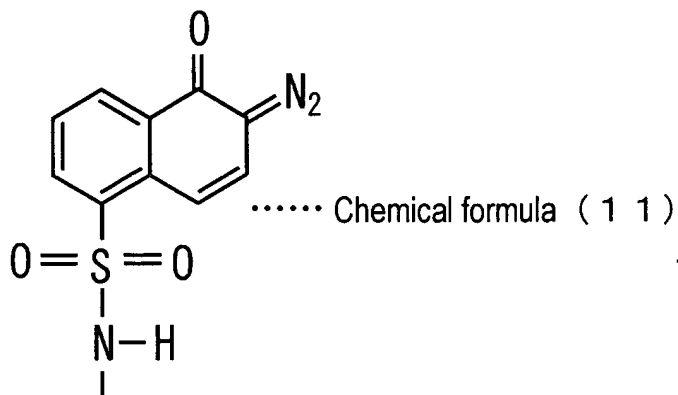
3. The resin composition of claim 1 wherein the photosensitizer is based on an o-quinone diazide compound represented by formula (12) below:



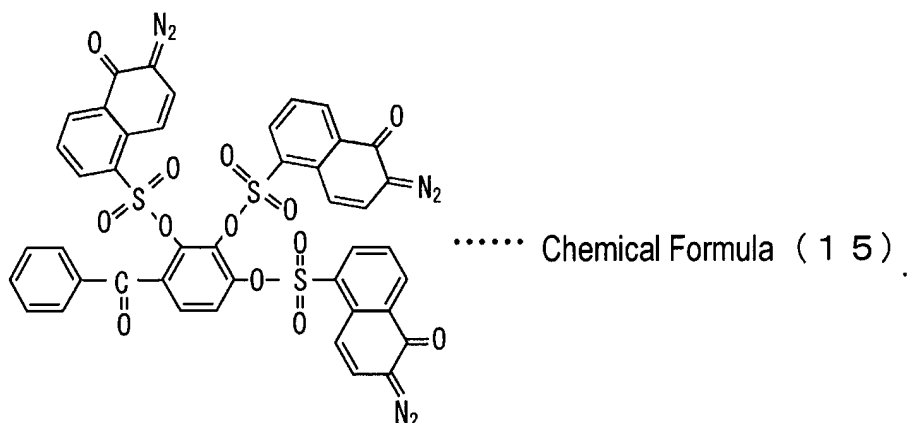
5 wherein chemical structure A³ represents any one of chemical structures selected from the group consisting of oxygen, sulfonyl, ketone and the chemical structures represented by chemical formulae (13) and (14) below, and substituents R⁶-R¹¹ represent any one of substituents selected from the group consisting of hydrogen,
 10 hydroxyl and the substituents represented by chemical formulae (6)-(11) below, provided that at least one of substituents R⁶- R¹¹ represents any one of substituents selected from the group consisting of the substituents represented by chemical formulae (6)-(8) below:







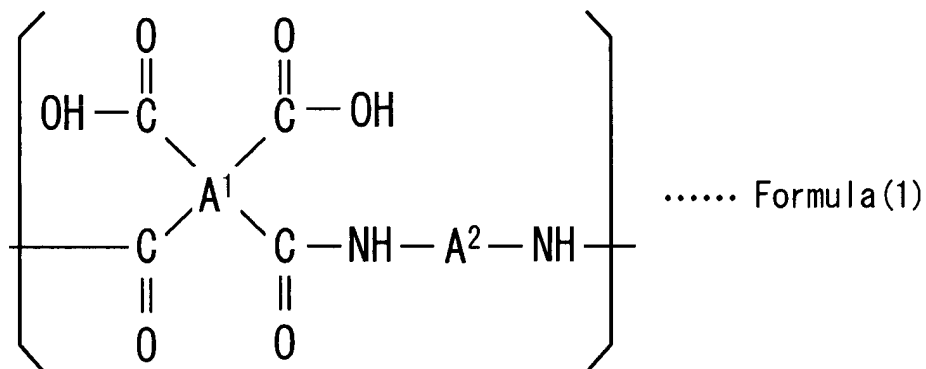
4. The resin composition of claim 5 wherein the o-quinone diazide compound is 2,3,4-trihydroxybenzophenone o-naphthoquinone diazide sulfonic ester represented by chemical formula (15) below:



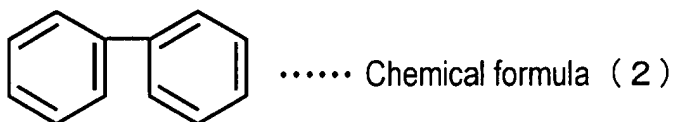
5

5. A process for forming a resin film comprising the steps of coating an object on which a resin film is to be formed with a resin composition containing a polyimide precursor having a polymer structure unit represented by formula (1) below and having an imidization degree of 7.5 % or more and 36 % or less and a photosensitizer to form a resin film, exposing the resin film to light to form a latent image, developing the resin film and heating

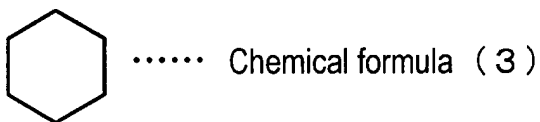
the resin film to imidize the polyimide precursor,



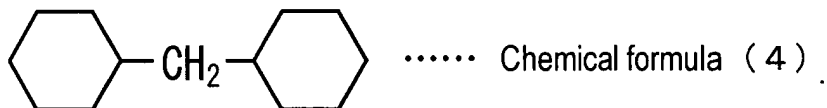
wherein the chemical structure represented by A¹ is biphenyl represented by chemical formula (2) below:



and the chemical structure represented by A² is an alicyclic compound
5 selected from either one of cyclohexane represented by chemical
formula (3) below:



or 4,4'-methylenebiscyclohexane represented by chemical formula
(4) below:

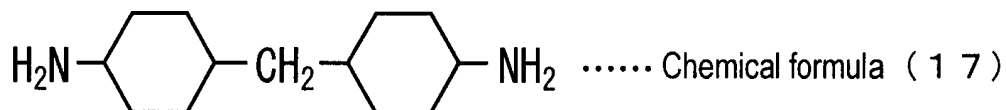


10 6. A process for preparing a resin composition comprising
reacting 1,4-diaminocyclohexane represented by chemical formula
(16) below:



with an aromatic dianhydride in a solvent to form a salt, reacting
 a resin solution containing the salt at a temperature of 80 °C or
 more and 150 °C or less, then reacting the resin solution at a
 temperature of 160 °C or more and 250 °C or less to a desired imidization
 5 degree and further adding a photosensitizer to the resin solution
 to give a resin composition.

7. A process for preparing a resin composition comprising
 reacting 4,4'-methylenebis(cyclohexylamine) represented by
 10 chemical formula (17) below:



with an aromatic dianhydride in a solvent to form a salt, reacting
 a resin solution containing the salt at a temperature of 80 °C or
 more and 150 °C or less, then reacting the resin solution at a
 temperature of 160 °C or more and 250 °C or less to a desired imidization
 15 degree and further adding a photosensitizer to the resin solution
 to give a resin composition.